

#### **Features**

Extremely Fast Switching Speed Low Forward Voltage Pb-Free Package is Available



## **Package Marking and Ordering Information**

Product ID	Pack	Marking	Qty(PCS)	
SBAT54XV2T5G	SOD-523	JV	3000	



# Maximum Ratings (Ta=25°C unless otherwise noted)

Parameter	Symbol	Limits	Unit
DC Reverse voltage	$V_R$	30	V
Continuous forward current	I <sub>F</sub>	200	mA
Peak forward surge current	I <sub>FSM</sub>	600	mA
Total power dissipation	P <sub>tot</sub>	200	mW
Total resistance junction to ambient	$R_{\theta JA}$	635	°C/W
Junction temperature	T <sub>j</sub>	150	°C
Storage temperature	T <sub>stg</sub>	-55-150	°C

# Electrical Characteristics(Ta=25°C unless otherwise specified)

Parameter	Symbol	Min.	Тур.	Max.	Unit	Conditions
Reverse breakdown voltage	$V_{(BR)R}$	30			V	I <sub>R</sub> =100μA
			0.22	0.24		I <sub>F</sub> =0.1mA
			0.41	0.5		I <sub>F</sub> =30mA
Forward voltage	$V_{F}$		0.52	0.8	V	I <sub>F</sub> =100mA
			0.29	0.32		I <sub>F</sub> =1.0mA
			0.35	0.40		I <sub>F</sub> =10mA
Reverse current	I <sub>R</sub>		0.5	2.0	μΑ	V <sub>R</sub> =25V
Diode capacitance	C <sub>d</sub>		7.6	10	pF	V <sub>R</sub> =1V,f=1MHz
Reverse recovery time	t <sub>rr</sub>			5	ns	I <sub>F</sub> =I <sub>R</sub> =10mA



# **Typical Characteristics**

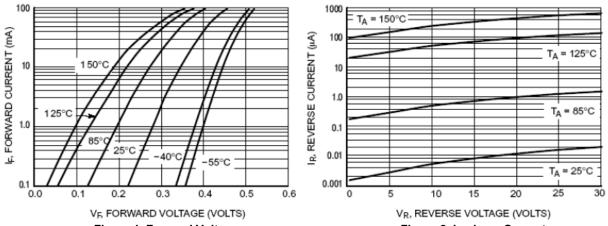


Figure 1. Forward Voltage

Figure 2. Leakage Current

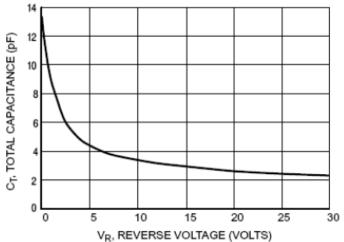
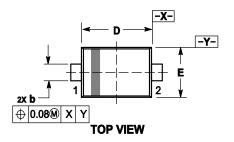
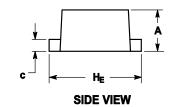


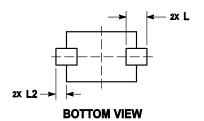
Figure 3. Total Capacitance



### **Outline And Dimensions**







#### Notes:

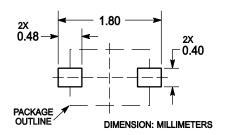
- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- 2. CONTROLLING DIMENSION: MILLIMETERS.
- 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD

THICKNESS OF BASE MATERIAL.

4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.50	0.60	0.70	0.020	0.024	0.028
b	0.25	0.30	0.35	0.010	0.012	0.014
С	0.07	0.14	0.20	0.003	0.006	0.008
D	1.10	1.20	1.30	0.043	0.047	0.051
Е	0.70	0.80	0.90	0.028	0.031	0.035
H <sub>E</sub>	1.50	1.60	1.70	0.059	0.063	0.067
┙	0.30 REF			0.012 REF		
L <sub>2</sub>	0.15	0.20	0.25	0.006	0.008	0.010

## **Soldering Footprint**





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